



Material Content Data Sheet



Sales Product Name		BCX 71H E6327		Issued		29. August 2013		
MA#		MA000484810						
Package		PG-SOT23-3-11		Weight*		8.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		5	
	noble metal	gold	7440-57-5	0.009	0.10		1041	
	inorganic material	silicon	7440-21-3	0.039	0.44	0.54	4450	5496
leadframe	non noble metal	chromium	7440-47-3	0.008	0.09		925	
	inorganic material	silicon	7440-21-3	0.001	0.01		62	
	non noble metal	titanium	7440-32-6	0.003	0.03		308	
	non noble metal	copper	7440-50-8	2.704	30.71	30.84	307094	308389
wire	noble metal	gold	7440-57-5	0.012	0.14	0.14	1416	1416
encapsulation	organic material	carbon black	1333-86-4	0.058	0.66		6566	
	plastics	brominated resin	-	0.087	0.98		9849	
	inorganic material	antimonytrioxide	1309-64-4	0.116	1.31		13131	
	plastics	epoxy resin	-	1.243	14.12		141162	
	inorganic material	silicondioxide	60676-86-0	4.278	48.60	65.67	485861	656569
leadfinish	non noble metal	tin	7440-31-5	0.150	1.70	1.70	16993	16993
plating	noble metal	silver	7440-22-4	0.098	1.11	1.11	11137	11137
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

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